ASSOCIATIO	Material Comp © Copyright 2005. I S INDUSTRIES international and Par	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.				This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lowe level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.									
1752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Distribute				* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi					als and Mfg Information				
Supplie	r Information														
ompany	name*	Company unique ID			ι	Unique ID Authority					Response Date*				
nsemi												2025-09-17			
Contact N	lame	Title - Contact]	Phone - Contact*					Email - Contact*				
Product-l	Env-Stewards	Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com					
uthorize	ed Representative*	Title - Representative			1	Phone - Representative*				Email - Representative*					
roduct-l	Env-Stewards	Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com					
	Requester Item Number Mfr Item		n Number Mfr Item Name			Effective Date	ctive Date Version Manufacturing Sit		ring Site	1	Weight*	UOM	Unit Type		
		AP1302CSSL00SMG 13 MP Co-Processo A0-DR1		sor		2025-09-17	125-09-17 MY5			6	58.1	mg	Each		
Ianufa	cturing Proccess Informa	tion													
	Terminal Plating / Grid Array Material		Ferminal Base Alloy J-STD-020 MS		Rating	Peak Process Body Temperatu		ure Max Time at Peak Temper		Temperat	ure Nur	nber of Reflow Cy	/cles		
SnAgCu		CU Alloy 4		l .		260 C		30 seco		secon	ds 3				
omments	3														
or more	information regarding material	composition]	please refer to	page 3											

RoHS Material Composition Declaration				Declaration Type *	Detailed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	IS RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).										
cadmium, hexavalentchromium, polybrominate contains a RoHS restricted substance inexcess encompass all such components. Supplier certif as of the date that Supplier completes this form Company acknowledges that Supplier may hav independently verified information provided by certification in this paragraph. If the Company a	ed biphenyls and/or polybrominated dip of an applicable quantity limit, please ir ies that it gathered the information it pro- .Supplier acknowledges that Company e relied on informationprovided by othe y others, Supplier agrees that, at a minin and the Supplier enter into a written agre pource of the Supplier's liability and the	henyl ethers (each a " ndicate below which, i ovides in this form us will rely on this certifiers in completing this num, itssuppliers have eement with respect to Company's remedies	RoHS restricted substance") in exce if any, RoHS exemption you believe ing appropriate methods to ensure if ication in determining the complian form, and that Supplier may not have e provided certifications regarding the to the identified part, the terms and cc for issues that arise regarding inform	ce of its products with European Union membe	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the anty rights and/or remedies provided as part of						
RoHS Declaration * 1 - Item(s)	does not contain RoHS restricted substa	on above	Supplier Acceptance	* Accepted							
Exemption: If the declared item does not con applicable exemptions.	ntain RoHS restricted substances per	the definition above	except for defined RoHS exempti	ons, then select the corresponding response i	n the RoHS Declaration above and choose all						
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructions: Complete all of the required fin Requester) and click on Submit Form to have	elds on all pages of this form. Select the form returned to the Requester	he "Accepted" on th	e Supplier Acceptance drop-down	. This will display the signature area. Digital	lly sign the declaration (if required by the						
Supplier Digital Signature Ra	stislav Drska	Le									

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	8.02	mg	Supplier	Silicon (Si)	7440-21-3		7.9903	mg
			Supplier	Polyimide	Proprietary Data		0.0297	mg
Die Attach	0.8	mg	Supplier	Epoxy resins	129915-35-1		0.06	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		0.436	mg
			Supplier	Acrylic resins	Proprietary Data		0.084	mg
			Supplier	Polyimide	Proprietary Data		0.22	mg
Iold Compound-Black	33.8	mg		Phenolic Resin	proprietary data		1.521	mg
			Supplier	Epoxy Phenol Resin	Proprietary Data		2.028	mg
			Supplier	Carbon Black (C)	1333-86-4		0.1014	mg
			Supplier	Aluminum Hydroxide (Al(OH)3)	21645-51-2		1.014	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		25.6542	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		3.4814	mg
older Ball	12.56	mg	Supplier	Silver (Ag)	7440-22-4		0.3768	mg
			Supplier	Tin (Sn)	7440-31-5		12.1204	mg
			Supplier	Copper (Cu)	7440-50-8		0.0628	mg
ubstrate and Solder Mask	12.31	mg	Supplier	Fiber Glass (SiO2)	65997-17-3		2.6085	mg
			В	Nickel (Ni)	7440-02-0		0.2339	mg
			Supplier	Gold (Au)	7440-57-5		0.0308	mg
			Supplier	Cured Resin of Solder Mask	Proprietary Data		1.7505	mg
			Supplier	Bismaleimide Triazine resin	Proprietary Data		1.6101	mg
			Supplier	Copper (Cu)	7440-50-8		6.0762	mg
Wire Bond - Au	0.61	mg	Supplier	Gold (Au)	7440-57-5		0.61	mg